

APPROVAL SHEET

RGTCM Series - 0806(3025)- RoHS Compliance

THIN FILM CERAMIC COMMON MODE FILTER

Halogens Free Product

P/N: RGTCM0806350H0T

*Contents in this sheet are subject to change without prior notice.

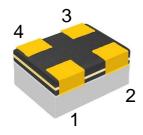
FEATURES

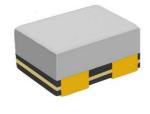
- 1. Miniature footprint: 0.8 X 0.6 X 0.5 mm³.
- 2. Thin Film Technology.
- 3. Reflow Solderable SMD Devices.
- 4. Wide Pass Band(Cut- Off Frequency: -3dB : 4/5/8GHz Typical).
- 5. High attenuation for common mode noise.
- 6. This product contains no lead and supports lead-free Ni/Au soldering

APPLICATIONS

- 1. For Super Speed Signal Line Application
- 2. LVDS/IEEE1394/HDMI/DVI/MIPI/USB3.0

CONSTRUCTION



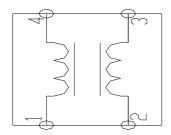


DIMENSIONS

Figure	Symbol	Dimension (mm)
W T B	L	0.88 ± 0.05
	W	0.68 ± 0.05
	Т	0.50 ± 0.05
	А	0.15 ± 0.05
	В	0.20 ± 0.05
A	С	0.27 ± 0.10
	D	0.62 ± 0.05
	E	0.50 ± 0.10
	F	0.82 ± 0.05



EQUIVALENT CIRCUIT



ELECTRICAL CHARACTERISTICS

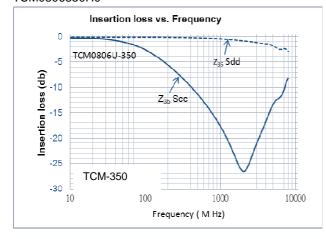
Туре	Common Mode	Max. DC	Rated	Rated	Cut off	Insulation
	Impedance	Resistance	Current	Voltage	Frequency	Resistance
	(Ω)	(Ω)	(mA)	Ed(V)	(GHz) typ.	(M Ω) min.
RGTCM0806350H0T	35±20%	1.8±30%	100	10	8G	10

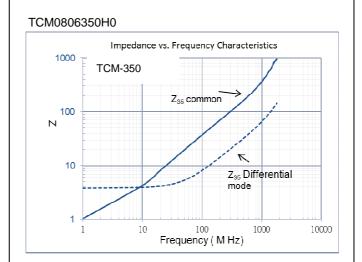
Operating temperature range : -40 $^{\circ}$ C to +85 $^{\circ}$ C

Typical electrical performance Impedance VS Frequency Characteristics

S-Parameter







SOLDER LAND PATTERN

Figure	Symbol	Dimension(mm)
В	А	0.90 ± 0.10
C	В	0.50 ± 0.10
	С	0.30 ± 0.10
◆ _D →	D	0.30± 0.10



RELIABILITY TEST

Test item	Test condition / Test method	Specific	ation
Solderability JIS C 0050-4.6 JESD22-B102D	*Solder bath temperature : $235 \pm 5^{\circ}$ C *Immersion time : 2 ± 0.5 sec *Solder : Sn3Ag0.5Cu for lead-free	At least 95% of a surface of each terminal electrode must be covered by fresh solder	
Leaching (Resistance to dissolution of metallization) IEC 60068-2-58	*Solder bath temperature : $260 \pm 5^{\circ}\text{C}$ *Leaching immersion time : $30 \pm 0.5 \text{ sec}$ *Solder : SN63A	Loss of metallization on the edges of each electrode shall not exceed 25%.	
Resistance to soldering heat JIS C 0050-5.4	*Preheating temperature : 120~150°C, 1 minute. *Solder temperature : 270±5°C *Immersion time : 10±1 sec *Solder : Sn3Ag0.5Cu for lead-free Measurement to be made after keeping at room temperature for 24±2 hrs	Loss of metallization on electrode shall not exce No mechanical damage Samples shall satisfy el after test, meet Table 1. Table 1 Appearance Common Mode	ed 25%. ectrical specification No damaged
	Toom temperature for 24±2 ms	Impedance Change DC Resistance Change	Within ± 20% Within ± 30%
Drop Test JIS C 0044 Vibration JIS C 0040	*Height: 75 cm *Test Surface: Rigid surface of concrete or steel. *Times: 6 surfaces for each units: 2 times for each side. *Frequency: 10Hz~55Hz~10Hz(1min) *Total amplitude: 1.5mm *Test times: 6hrs.(Two hrs each in three mutually perpendicular directions)	No mechanical damage Samples shall satisfy el after test, meet Table 1.	ectrical specification
Bending test JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and	No mechanical damage. Samples shall satisfy electrical specafter test, meet Table 2. Table 2	
	then pressure shall be maintained for 5±1 sec. Measurement to be made after keeping at room temperature for 24±2 hours	Appearance DC Resistance Change	No damaged Within ± 30%

Temperature cycle JIS C 0025	 30±3 minutes at -40°C±3°C, 10~15 minutes at room temperature, 30±3 minutes at +85°C±3°C, 10~15 minutes at room temperature, Total 100 continuous cycles Measurement to be made after keeping at room temperature for 24±2 hrs 	No mechanical damage. Samples shall satisfy electrical specification after test, meet Table 1.
High temperature JIS C 0021	*Temperature: 85°C±2°C *Test duration: 1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Samples shall satisfy electrical specification after test, meet Table 1.
Humidity (steady conditions) JIS C 0022	*Humidity: 90% to 95% R.H. *Temperature: 40±2°C *Time: 1000+24/-0 hrs. Measurement to be made after keeping at room temperature for 24±2 hrs % 500hrs measuring the first data then 1000hrs data	No mechanical damage. Samples shall satisfy electrical specification after test, meet Table 1.
Low temperature JIS C 0020	*Temperature : -40°C±2°C *Test duration : 1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Samples shall satisfy electrical specification after test, meet Table 1.

SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

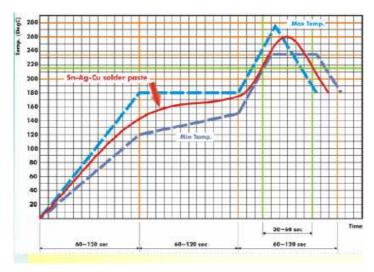


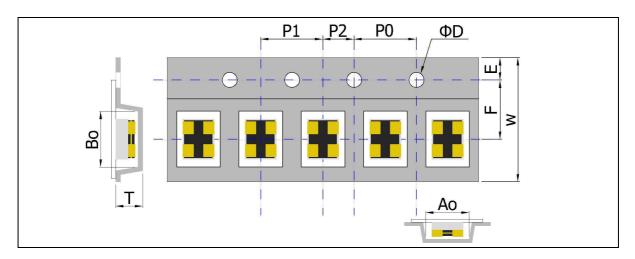
Fig 2. Infrared soldering profile

ORDERING CODE

RG	TCM	0806	350	Н	0	Т
Walsin	Product code	Dimension	СМ	Application	Specification	Packing
RG device	TCM:	code	Impedance	H:	Code from 0~9	T : Reeled
	Thin Film	0806 =	350 : 35 ohm	HDMI/DVI/LVDS	dependent on	
	Common	Length 08		/SATA/PCI-/D-	different electrical	
	Mode Filter	Width 06,		Port	specification	

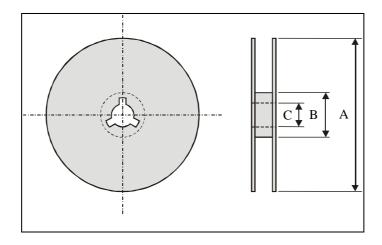
Minimum Ordering Quantity: 10000 pcs per reel.

PACKAGING



Index	A ₀	B ₀	ΦD	Т	W
Dimension(mm)	0.78±0.03	1.04±0.03	1.55±0.05	0.6±0.03	8.0±0.10
Index	E	F	P ₀	P ₁	P ₂
Dimension(mm)	1.75±0.05	3.5±0.05	4.0±0.10	4.0±0.10	2.0±0.05

Reel dimensions



Index	А	В	С
Dimension (mm)	Ф178.0	Ф60.0	Ф13.0

Taping Quantity:10000 pieces per 7" reel

CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

Products should be storage in the warehouse on the following conditions.

■ Temperature : -10 to +40°C

Humidity : 30 to 70% relative humidity

- Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
- Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be storage under the airtight packaged condition.